

Q1: What is RoHS?

A1: RoHS is an acronym for the “Restriction of Hazardous Substances” Directive. It is short for “The Directive on the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment 2002/95/EC”. This directive, adopted by the European Union and put into effect July 1, 2006, restricts the concentration of lead, cadmium, mercury, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ether (PBDE) in electrical and electronic equipment.

Q2: How does RoHS compliance affect CardLogix products?

A1: All products manufactured or sold by CardLogix are now certified to be RoHS compliant, effective immediately. You can obtain both sample and production quantities for evaluation as soon as you wish.

Q3: Are there part number changes?

A3: No, all current part numbers will be retained.


Q4: Will packaging or parts be clearly labeled as Lead-Free or RoHS compliant?

A4: Yes, all RoHS compliant components will be clearly labeled as Lead-Free and RoHS compliant.

Q5: Are there price changes?

A5: No price changes for RoHS compliant components are expected.

Visit <http://www.rohs.eu/> for complete information on RoHS regulation.

Ag	The abbreviation for the element “Silver”.
Au	The abbreviation for the element “Gold”.
Backwards compatible	This term applies to RoHS compliant component compatibility to legacy Sn-Pb soldering processes. NIC RoHS components are reverse/backwards compatible .
Bi	The abbreviation for the element “Bismuth”.
Cd	The abbreviation for the element “Cadmium”.
Cu	The abbreviation for the element “Copper”.
Green statement	RoHS compliance statement (CofC) covering specific product series or family.
Hg	The abbreviation for the element “Mercury”.
Homogeneous material	Homogeneous materials are defined as materials that cannot be mechanically disjointed into different materials and are “of uniform composition throughout”. Types include: liquids, plastics, ceramics, glass, metals, alloys, papers, resins, and coatings.
In	The abbreviation for the element “Indium”.
MCV	Maximum Concentration Values define the greatest acceptable amount of a restricted substance (as defined by the EU RoHS directive) within each homogeneous material that a component is composed of.
MDS	Material Declaration Statements are documents--typically worksheets--that provides details about the amount of materials and substances that are used within a particular component.
MDL	Moisture Sensitivity Levels, defined by IPC/JEDEC J-STD-20 , are standard measures of the varying degrees of popcorn cracking tendency of various package types.
Pb	The abbreviation for the element “Pb”.
Pb-Free  Pb-Free	An abbreviation for “Lead-Free”. Lead-free devices cannot contain more than 0.01% lead within each homogeneous material that compose the component.
PCN	An abbreviation for “Product Change Notification”.
RoHS	Short for “The Directive on the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment 2002/95/EC”.
SAC	An acronym for Tin-Silver-Copper (Sn-Ag-Cu) solder alloy, used for RoHS compliance.
SAC305	Used to identify an alloy of Sn96.5Ag3.0Cu0.5, deemed as the best candidate to replace tin-lead solder.
Sb	The abbreviation for the element “Antimony”.
Sn	The abbreviation for the element “Tin”.
Sn-Pb	An abbreviation for legacy Tin-Lead solder (specifically Sn63) alloy. It is being phased out by the RoHS and WEEE directives.
WEEE	An acronym for the “Waste Electrical and Electronic Equipment” Directive (European Union Directive 2002/96/EC), which holds manufacturers responsible for e-waste disposal at the end of an electrical or electronic device’s life.